

IN THE CLAIMS

Cancel claims 1-25 and 32-42.

1 - 25 (Canceled)

26. (Original) A method of bonding a first body to a second body comprising the steps of:

disposing between the first body and the second body, a reactive multilayer foil and at least one melttable joining material, the reactive multilayer foil having a plurality of openings through the thickness of the foil;

pressing the bodies together against the foil and the joining material; and igniting the reactive foil to melt the joining material and permit the melted material to flow through the openings to join the first and second bodies.

27. (Original) The method of claim 26 wherein at least one of first body or the second body comprise a semiconductor or a microelectronic device.

28. (Original) The method of claim 26 wherein the first body and the second body have CTEs that differ by more than about 1 $\mu$ m/m/ $^{\circ}$ C.

29. (Original) The product made by the method of claim 26.

30. (Original) The product made by the method of claim 27.

31. (Original) The product made by the method of claim 28.

32 - 42 (Canceled)